

BEST AVAILABLE COPY

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10078243	02/14/2002	287	612	2815	Gurley

****APPLICANTS:** Kripesh Vaidyanathan; iyer Mahadevan; Lim Thiam;
438 - 2812

****CONTINUING DATA VERIFIED:**
THIS APPLN CLAIMS BENEFIT OF 60/269,500 02/16/2001 *Method eliter*

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	ALLEN4.001AUS
Verified and Acknowledged Examiner's initials	
TITLE : Process of forming metal surfaces compatible with a wire bonding and semiconductor integrated circuits manufactured by the process	

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
		Sheets Drawg.	Figs. Drawg.
		Print Fig.	
Primary Examiner		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

(Attached in pocket on right inside flap)